

## PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2707641

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT										
NATURE OF CONVEYANCE:	Corrective Assignment to correct the TYPOGRAPHICAL ERROR IN THE INVENTOR NAME. previously recorded on Reel 032067 Frame 0078. Assignor (s) hereby confirms the ASSIGNMENT.										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JIE CHEN</td> <td>01/23/2014</td> </tr> <tr> <td>HSIEN-WEI CHEN</td> <td>01/23/2014</td> </tr> </tbody> </table>		Name	Execution Date	JIE CHEN	01/23/2014	HSIEN-WEI CHEN	01/23/2014				
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HSIEN-WEI CHEN	01/23/2014										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	Street Address:	NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK	City:	HSINCHU	State/Country:	TAIWAN	Postal Code:	300
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.										
Street Address:	NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK										
City:	HSINCHU										
State/Country:	TAIWAN										
Postal Code:	300										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14166531</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14166531						
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Application Number:	14166531										
CORRESPONDENCE DATA											
Fax Number:	(202)756-8087										
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
Correspondent Name:	MCDERMOTT WILL & EMERY LLP										
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Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20001										
ATTORNEY DOCKET NUMBER:	050094-0184										
NAME OF SUBMITTER:	TARA JEFFERS										
Signature:	/tara jeffers/										

Date:

01/31/2014

**Total Attachments: 5**

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*Electronic Patent Assignment System*

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<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
Stylesheet Version v1.2

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT						
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT						
<b>CONVEYING PARTY DATA</b>							
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JIE CHEN</td> <td>01/23/2014</td> </tr> <tr> <td>HSIEH-WEI CHEN HSIEN-WEI CHEN</td> <td>01/23/2014</td> </tr> </tbody> </table>		Name	Execution Date	JIE CHEN	01/23/2014	HSIEH-WEI CHEN HSIEN-WEI CHEN	01/23/2014
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<b>RECEIVING PARTY DATA</b>							
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.						
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6, SCIENCE BASED						
<b>Internal Address:</b>	INDUSTRIAL PARK						
<b>City:</b>	HSINCHU						
<b>State/Country:</b>	TAIWAN						
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<b>CORRESPONDENCE DATA</b>							
<b>Fax Number:</b>	(202)756-8087						

<b>Phone:</b>	202-756-8000
<b>Email:</b>	ipdocketmwe@mwe.com
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>	
<b>Correspondent Name:</b>	MCDERMOTT WILL & EMERY LLP
<b>Address Line 1:</b>	THE MCDERMOTT BUILDING
<b>Address Line 2:</b>	500 NORTH CAPITOL STREET, N.W.
<b>Address Line 4:</b>	WASHINGTON, DISTRICT OF COLUMBIA 20001
<b>ATTORNEY DOCKET NUMBER:</b>	050094-0184
<b>NAME OF SUBMITTER:</b>	STEPHEN A. BECKER
<b>Signature:</b>	/stephen a. becker/
<b>Date:</b>	01/28/2014
<b>Total Attachments: 2</b> source=ASSIGNMENT#page1.tif source=ASSIGNMENT#page2.tif	
<b>RECEIPT INFORMATION</b>	
<b>EPAS ID:</b>	PAT2702050
<b>Receipt Date:</b>	01/28/2014

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**ASSIGNMENT**

This assignment agreement is applicable to an invention entitled (Invention Title) \_\_\_\_\_  
SEMICONDUCTOR DEVICE WITH BUMP STOP STRUCTURE

The PATENT RIGHTS referred to in this agreement are:

(check one)  a patent application for this invention, executed by the ASSIGNOR(S)  
 concurrently with this assignment.

U.S. patent application Serial No. \_\_\_\_\_, filed \_\_\_\_\_

a U.S. patent application based on PCT International Application  
 No. \_\_\_\_\_ filed on (date) \_\_\_\_\_ (U.S. patent application  
 Serial No. \_\_\_\_\_, if known).

U.S. patent No. \_\_\_\_\_, issued \_\_\_\_\_.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of  
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one)  U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to  
 claim the benefit of the filing date of any U.S. or foreign patent application  
 for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures  
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.

(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,  
 TAIWAN 300, R.O.C.

The ASSIGNEE is:

(check one)  An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) \_\_\_\_\_

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and  
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following  
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable  
 provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO  
ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.  
INVENTION TITLE: SEMICONDUCTOR DEVICE WITH BUMP STOP  
STRUCTURE

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Jie CHEN</u> Name of sole or first inventor	<u>Jie Chen</u> Signature	<u>2014.1.23</u> Date
<u>Hsien-Wei CHEN</u> Name of second inventor, if any	<u>Hsien-Wei Chen</u> Signature	<u>2014.1.23</u> Date